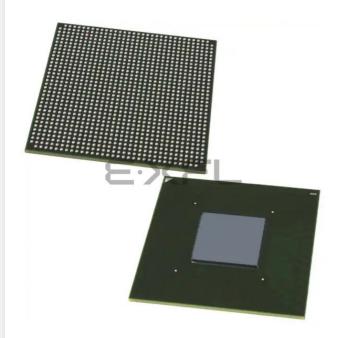
Intel - 5AGXFB7H4F35I5N Datasheet





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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Details	
Product Status	Obsolete
Number of LABs/CLBs	23780
Number of Logic Elements/Cells	504000
Total RAM Bits	27695104
Number of I/O	544
Number of Gates	
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA Exposed Pad
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxfb7h4f35i5n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



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Arria V GX, GT, SX, and ST Device Datasheet



This datasheet describes the electrical characteristics, switching characteristics, configuration specifications, and I/O timing for Arria® V devices.

Arria V devices are offered in commercial and industrial grades. Commercial devices are offered in -C4 (fastest), -C5, and -C6 speed grades. Industrial grade devices are offered in the -I3 and -I5 speed grades.

Related Information

Arria V Device Overview

Provides more information about the densities and packages of devices in the Arria V family.

Electrical Characteristics

The following sections describe the operating conditions and power consumption of Arria V devices.

Operating Conditions

Arria V devices are rated according to a set of defined parameters. To maintain the highest possible performance and reliability of the Arria V devices, you must consider the operating requirements described in this section.

Absolute Maximum Ratings

This section defines the maximum operating conditions for Arria V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms.

The functional operation of the device is not implied for these conditions.

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Symbol	Description	Minimum ⁽⁵⁾	Typical	Maximum ⁽⁵⁾	Unit
V _{CCL_GXBL}	GX and SX speed grades—clock network power (left side)	1.08/1.12	$1.1/1.15^{(6)}$	1.14/1.18	V
V _{CCL_GXBR}	GX and SX speed grades—clock network power (right side)	1.00/1.12	1.1/1.13	1.14/1.10	v
V _{CCL_GXBL}	GT and ST speed grades—clock network power (left side)	1.17	1.20	1.23	V
V _{CCL_GXBR}	GT and ST speed grades—clock network power (right side)	1.17	1.20	1.23	v

Related Information

Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines

Provides more information about the power supply connection for different data rates.

HPS Power Supply Operating Conditions

Table 1-5: HPS Power Supply Operating Conditions for Arria V SX and ST Devices

This table lists the steady-state voltage and current values expected from Arria V system-on-a-chip (SoC) devices with ARM®-based hard processor system (HPS). Power supply ramps must all be strictly monotonic, without plateaus. Refer to Recommended Operating Conditions for Arria V Devices table for the steady-state voltage values expected from the FPGA portion of the Arria V SoC devices.

Symbol	Description	Condition	Minimum ⁽⁷⁾	Typical	Maximum ⁽⁷⁾	Unit
	HPS core	-C4, -I5, -C5, -C6	1.07	1.1	1.13	V
V _{CC_HPS}	voltage and periphery circuitry power supply	-I3	1.12	1.15	1.18	V

⁽⁵⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.



⁽⁷⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

			V _{CCIO} (V)												
Parameter	Symbol	Condition	1	.2	1	.5	1.	.8	2	.5	3	.0	3.	.3	Unit
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus-hold trip point	V _{TRIP}	_	0.3	0.9	0.375	1.125	0.68	1.07	0.7	1.7	0.8	2	0.8	2	V

OCT Calibration Accuracy Specifications

If you enable on-chip termination (OCT) calibration, calibration is automatically performed at power up for I/Os connected to the calibration block.

Table 1-8: OCT Calibration Accuracy Specifications for Arria V Devices

Calibration accuracy for the calibrated on-chip series termination (R_S OCT) and on-chip parallel termination (R_T OCT) are applicable at the moment of calibration. When process, voltage, and temperature (PVT) conditions change after calibration, the tolerance may change.

Symbol	Symbol Description		Ca	alibration Accura	су	Unit
Symbol	Description	Condition (V)	–I3, –C4	–I5, –C5	-C6	Ont
25-Ω R _S	Internal series termination with calibration (25- Ω setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2	±15	±15	±15	%
50-Ω R _S	Internal series termination with calibration (50- Ω setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2	±15	±15	±15	%
34- Ω and 40- Ω R_S	Internal series termination with calibration (34- Ω and 40- Ω setting)	V _{CCIO} = 1.5, 1.35, 1.25, 1.2	±15	±15	±15	%
48- Ω , 60- Ω , and 80- Ω R _S	Internal series termination with calibration (48- Ω , 60- Ω , and 80- Ω setting)	$V_{CCIO} = 1.2$	±15	±15	±15	%
50-Ω R _T	Internal parallel termination with calibration ($50-\Omega$ setting)	V _{CCIO} = 2.5, 1.8, 1.5, 1.2	-10 to +40	-10 to +40	-10 to +40	%
20- Ω , 30- Ω , 40- Ω ,60- Ω , and 120- Ω R _T	Internal parallel termination with calibration (20- Ω , 30- Ω , 40- Ω , 60- Ω , and 120- Ω setting)	V _{CCIO} = 1.5, 1.35, 1.25	-10 to +40	-10 to +40	-10 to +40	%



Symbol	Description	V _{CCIO} (V)	Value	Unit
		3.0	0.189	
		2.5	0.208	
		1.8	0.266	-
dR/dT	OCT variation with temperature without recalibration	1.5	0.273	%/°C
		1.35	0.200	
		1.25	0.200	-
		1.2	0.317	

Pin Capacitance

Table 1-11: Pin Capacitance for Arria V Devices

Symbol	Description	Maximum	Unit
C _{IOTB}	Input capacitance on top/bottom I/O pins	6	pF
C _{IOLR}	Input capacitance on left/right I/O pins	6	pF
C _{OUTFB}	Input capacitance on dual-purpose clock output/feedback pins	6	pF
C _{IOVREF}	Input capacitance on V _{REF} pins	48	pF

Hot Socketing

Table 1-12: Hot Socketing Specifications for Arria V Devices

Symbol	Description	Maximum	Unit
I _{IOPIN (DC)}	DC current per I/O pin	300	μΑ
I _{IOPIN (AC)}	AC current per I/O pin	8(10)	mA
I _{XCVR-TX (DC)}	DC current per transceiver transmitter (TX) pin	100	mA

Arria V GX, GT, SX, and ST Device Datasheet

Altera Corporation



1-40 Transceiver Compliance Specification

Quartus Prime 1st								
Post Tap Pre- Emphasis Setting	10 (200 mV)	20 (400 mV)	30 (600 mV)	35 (700 mV)	40 (800 mV)	45 (900 mV)	50 (1000 mV)	Unit
16	_	_	9.56	7.73	6.49		_	dB
17	_	_	10.43	8.39	7.02		_	dB
18	_		11.23	9.03	7.52		_	dB
19	_		12.18	9.7	8.02		_	dB
20	_	_	13.17	10.34	8.59	_	_	dB
21	_	_	14.2	11.1	—	_	_	dB
22	_		15.38	11.87			_	dB
23	_	_	—	12.67	—		_	dB
24	_			13.48	_		_	dB
25	_			14.37	—		_	dB
26	_	_	_	_	_	_	_	dB
27	_				_		_	dB
28							_	dB
29	_				—		_	dB
30	_				_		_	dB
31							—	dB

Related Information

SPICE Models for Altera Devices

Provides the Arria V HSSI HSPICE models.

Transceiver Compliance Specification

The following table lists the physical medium attachment (PMA) specification compliance of all supported protocol for Arria V GX, GT, SX, and ST devices. For more information about the protocol parameter details and compliance specifications, contact your Altera Sales Representative.



Table 1-38: Memory Block Performance Specifications for Arria V Devices

Memory	Mode	Resourc	es Used		Performance		Unit
Memory	Mode	ALUTs	Memory	-I3, -C4	–I5, –C5	-C6	Onit
	Single port, all supported widths	0	1	500	450	400	MHz
	Simple dual-port, all supported widths	0	1	500	450	400	MHz
MLAB	Simple dual-port with read and write at the same address	0	1	400	350	300	MHz
	ROM, all supported width	—		500	450	400	MHz
	Single-port, all supported widths	0	1	400	350	285	MHz
	Simple dual-port, all supported widths	0	1	400	350	285	MHz
Block write	Simple dual-port with the read-during- write option set to Old Data , all supported widths	0	1	315	275	240	MHz
	True dual port, all supported widths	0	1	400	350	285	MHz
	ROM, all supported widths	0	1	400	350	285	MHz

Internal Temperature Sensing Diode Specifications

Table 1-39: Internal Temperature Sensing Diode Specifications for Arria V Devices

Temperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
-40 to 100°C	±8°C	No	1 MHz	< 100 ms	8 bits	8 bits

Periphery Performance

This section describes the periphery performance, high-speed I/O, and external memory interface.

Actual achievable frequency depends on design and system specific factors. Ensure proper timing closure in your design and perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.



Figure 1-12: USB Timing Diagram



Ethernet Media Access Controller (EMAC) Timing Characteristics

Table 1-56: Reduced Gigabit Media Independent Interface (RGMII) TX Timing Requirements for Arria V Devices

Symbol	Description	Min	Тур	Max	Unit
T _{clk} (1000Base-T)	TX_CLK clock period	_	8	_	ns
T _{clk} (100Base-T)	TX_CLK clock period	—	40		ns
T _{clk} (10Base-T)	TX_CLK clock period	_	400		ns
T _{dutycycle}	TX_CLK duty cycle	45		55	%
T _d	TX_CLK to TXD/TX_CTL output data delay	-0.85		0.15	ns

Figure 1-13: RGMII TX Timing Diagram





1-80 AS Configuration Timing

Symbol	Parameter	Minimum	Maximum	Unit
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLк period	_	
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (T_{init} × CLKUSR period)		_
T _{init}	Number of clock cycles required for device initialization	8,576		Cycles

Related Information

FPP Configuration Timing

Provides the FPP configuration timing waveforms.

AS Configuration Timing

Table 1-68: AS Timing Parameters for AS ×1 and ×4 Configurations in Arria V Devices

The minimum and maximum numbers apply to both the internal oscillator and CLKUSR when either one is used as the clock source for device configuration.

The t_{CF2CD} , t_{CF2ST0} , t_{CFG} , t_{STATUS} , and t_{CF2ST1} timing parameters are identical to the timing parameters for passive serial (PS) mode listed in PS Timing Parameters for Arria V Devices table. You can obtain the t_{CF2ST1} value if you do not delay configuration by externally holding nSTATUS low.

Symbol	Parameter	Minimum	Maximum	Unit
t _{CO}	DCLK falling edge to the AS_DATA0/ASDO output		2	ns
t _{SU}	Data setup time before the falling edge on DCLK	1.5	_	ns
t _{DH}	Data hold time after the falling edge on DCLK	0		ns
t _{CD2UM}	CONF_DONE high to user mode	175	437	μs
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (T_{init} × Clkusr period)		_
T _{init}	Number of clock cycles required for device initialization	8,576		Cycles



1-100 Document Revision History

Date	Version	Changes
November 2012	3.0	 Updated Table 2, Table 4, Table 9, Table 14, Table 16, Table 17, Table 20, Table 21, Table 25, Table 29, Table 36, Table 56, Table 57, and Table 60. Removed table: Transceiver Block Jitter Specifications for Arria V Devices. Added HPS information: Added "HPS Specifications" section. Added Table 38, Table 39, Table 40, Table 41, Table 42, Table 43, Table 44, Table 45, Table 46, Table 47, Table 48, Table 49, and Table 50. Added Figure 7, Figure 8, Figure 9, Figure 10, Figure 11, Figure 12, Figure 13, Figure 14, Figure 15, Figure 16, Figure 17, Figure 18, and Figure 19. Updated Table 3 and Table 5.
October 2012	2.4	 Updated Arria V GX V_{CCR_GXBL/R}, V_{CCT_GXBL/R}, and V_{CCL_GXBL/R} minimum and maximum values, and data rate in Table 4. Added receiver V_{ICM} (AC coupled) and V_{ICM} (DC coupled) values, and transmitter V_{OCM} (AC coupled) and V_{OCM} (DC coupled) values in Table 20 and Table 21.
August 2012	2.3	Updated the SERDES factor condition in Table 30.
July 2012	2.2	 Updated the maximum voltage for V_I (DC input voltage) in Table 1. Updated Table 20 to include the Arria V GX -I3 speed grade. Updated the minimum value of the fixedclk clock frequency in Table 20 and Table 21. Updated the SERDES factor condition in Table 30. Updated Table 50 to include the IOE programmable delay settings for the Arria V GX -I3 speed grade.
June 2012	2.1	Updated $V_{CCR_GXBL/R}$, $V_{CCT_GXBL/R}$, and $V_{CCL_GXBL/R}$ values in Table 4.



Symbol	Description	Minimum ⁽¹¹⁸⁾	Typical	Maximum ⁽¹¹⁸⁾	Unit		
		0.82	0.85	0.88			
V _{CCR_GXBL} ⁽¹²¹⁾	Receiver analog power supply (left side)	0.97	1.0	1.03	V		
		1.03	1.05	1.07			
		0.82	0.85	0.88			
V _{CCR_GXBR} ⁽¹²¹⁾	Receiver analog power supply (right side)	0.97	1.0	1.03	V		
		1.03	1.05	1.07			
		0.82	0.85	0.88			
V _{CCT_GXBL} ⁽¹²¹⁾	Transmitter analog power supply (left side)	0.97	1.0	1.03	V		
		1.03	1.05	1.07			
		0.82	0.85	0.88			
V _{CCT_GXBR} ⁽¹²¹⁾	Transmitter analog power supply (right side)	0.97	1.0	1.03	V		
		1.03	1.05	1.07			
V _{CCH_GXBL}	Transmitter output buffer power supply (left side)	1.425	1.5	1.575	V		
V _{CCH_GXBR}	Transmitter output buffer power supply (right side)	1.425	1.5	1.575	V		



⁽¹¹⁸⁾ This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

⁽¹²¹⁾ This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rate up to 6.5 Gbps, you can connect this supply to 0.85 V.

Table 2-19: Differential SSTL I/O Standards for Arria V GZ Devices

I/O Standard		V _{CCIO} (V)		V _{SWIN}	_{G(DC)} (V)		$V_{X(AC)}(V)$			V _{SWING(AC)} (V)
	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Мах
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	V _{CCIO} + 0.6	V _{CCIO} /2 - 0.2	_	V _{CCIO} /2 + 0.2	0.62	$V_{CCIO} + 0.6$
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	V _{CCIO} + 0.6	V _{CCIO} /2 - 0.175		V _{CCIO} /2 + 0.175	0.5	V _{CCIO} + 0.6
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	(127)	V _{CCIO} /2 - 0.15		V _{CCIO} /2 + 0.15	0.35	_
SSTL-135 Class I, II	1.283	1.35	1.45	0.2	(127)	V _{CCIO} /2 - 0.15	V _{CCIO} /2	V _{CCIO} /2 + 0.15	2(V _{IH(AC)} - V _{REF})	$2(V_{IL(AC)} - V_{REF})$
SSTL-125 Class I, II	1.19	1.25	1.31	0.18	(127)	V _{CCIO} /2 - 0.15	V _{CCIO} /2	V _{CCIO} /2 + 0.15	2(V _{IH(AC)} - V _{REF})	_
SSTL-12 Class I, II	1.14	1.2	1.26	0.18	—	V _{REF} -0.15	V _{CCIO} /2	V _{REF} + 0.15	-0.30	0.30

Table 2-20: Differential HSTL and HSUL I/O Standards for Arria V GZ Devices

I/O Standard	V _{CCIO} (V)		V _{DIF(DC)} (V)			V _{X(AC)} (V)		V _{CM(DC)} (V)			V _{DIF(AC)} (V)		
	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	_	0.78		1.12	0.78	_	1.12	0.4	_
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	_	0.68		0.9	0.68	_	0.9	0.4	—



 $^{^{(127)}}$ The maximum value for $V_{SWING(DC)}$ is not defined. However, each single-ended signal needs to be within the respective single-ended limits ($V_{IH(DC)}$ and $V_{IL(DC)}$).

Mode ⁽¹⁶⁴⁾	Transceiver	PMA Width	20	20	16	16	10	10	8	8
	Speed Grade	PCS/Core Width	40	20	32	16	20	10	16	8
Dogistor	2	C3, I3L core speed grade	9.9	9	7.92	7.2	4.9	4.,5	3.92	3.6
Register	3	C4, I4 core speed grade	8.8	8.2	7.04	6.56	4.4	4.1	3.52	3.28

Related Information

Operating Conditions on page 2-1

10G PCS Data Rate

Table 2-31: 10G PCS Approximate Maximum Data Rate (Gbps) for Arria V GZ Devices

Mode ⁽¹⁶⁵⁾	Transceiver Speed	PMA Width	64	40	40	40	32	32
Mode	Grade	PCS Width	64	66/67	50	40	64/66/67	32
FIFO	2	C3, I3L core speed grade	12.5	12.5	10.69	12.5	10.88	10.88
	3	C4, I4 core speed grade	10.3125	10.3125	10.69	10.3125	9.92	9.92
Register	2	C3, I3L core speed grade	12.5	12.5	10.69	12.5	10.88	10.88
	3	C4, I4 core speed grade	10.3125	10.3125	10.69	10.3125	9.92	9.92

⁽¹⁶⁴⁾ The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.



⁽¹⁶⁵⁾ The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

2-42 Memory Block Specifications

Mode	Performar	nce		Unit	
imoue	C3, I3L	C4	14	onit	
One sum of two 27×27	380	300	MHz		
One sum of two 36×18	380	30	MHz		
One complex 18 × 18	400	35	MHz		
One 36 × 36	380	30	00	MHz	
Modes using Three DSP Blocks		•			
One complex 18 × 25	340	275	265	MHz	
Modes using Four DSP Blocks					
One complex 27×27	350	31	MHz		

Memory Block Specifications

Table 2-36: Memory Block Performance Specifications for Arria V GZ Devices

To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL set to **50%** output duty cycle. Use the Quartus II software to report timing for this and other memory block clocking schemes.

When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in F_{MAX}.

Memory	Mode	Resou	rces Used		Unit			
	Moue	ALUTs	Memory	C3	C4	I3L	14	Onic
	Single port, all supported widths	0	1	400	315	400	315	MHz
MLAB	Simple dual-port, x32/x64 depth	0	1	400	315	400	315	MHz
MLAD	Simple dual-port, x16 depth (178)	0	1	533	400	533	400	MHz
	ROM, all supported widths	0	1	500	450	500	450	MHz

⁽¹⁷⁸⁾ The F_{MAX} specification is only achievable with Fitter options, **MLAB Implementation In 16-Bit Deep Mode** enabled.



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Symbol	Conditions		C3, I3I	L		Unit		
Symbol	Conditions	Min	Тур	Мах	Min	Тур	Max	Onic
f _{HSCLK_in} (input clock frequency) True Differential I/O Standards ⁽¹⁷⁹⁾	Clock boost factor W = 1 to 40 $^{(180)}$	5	_	625	5		525	MHz
f _{HSCLK_in} (input clock frequency) Single Ended I/O Standards	Clock boost factor W = 1 to 40 $^{(180)}$	5		625	5	_	525	MHz
f _{HSCLK_in} (input clock frequency) Single Ended I/O Standards	Clock boost factor W = 1 to 40 $^{(180)}$	5	_	420	5	_	420	MHz
f _{HSCLK_OUT} (output clock frequency)	_	5	_	625 (181)	5	—	525 (181)	MHz

Transmitter High-Speed I/O Specifications

Table 2-40: Transmitter High-Speed I/O Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.



 $^{^{(179)}\,}$ This only applies to DPA and soft-CDR modes.

⁽¹⁸⁰⁾ Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.

⁽¹⁸¹⁾ This is achieved by using the LVDS clock network.

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Symbol	Conditions	C3, I3L		C4, I4			Unit	
Symbol	Conditions	Min	Тур	Мах	Min	Тур	Мах	Onic
t _{x litter} - True Differential I/O	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	160	_	_	160	ps
Standards	Total Jitter for Data Rate < 600 Mbps	_	_	0.1	_		0.1	UI
t _{x Jitter} - Emulated Differential I/O Standards with Three	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	—	_	300	_		325	ps
External Output Resistor Network	Total Jitter for Data Rate < 600 Mbps	_	_	0.2	_		0.25	UI
t _{DUTY}	Transmitter output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	%
	True Differential I/O Standards		_	200			200	ps
t _{RISE} & t _{FALL}	Emulated Differential I/O Standards with three external output resistor networks	_	_	250	_	_	300	ps
	True Differential I/O Standards			150			150	ps
TCCS	Emulated Differential I/O Standards		—	300			300	ps

Receiver High-Speed I/O Specifications

Table 2-41: Receiver High-Speed I/O Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.



2-50 Soft CDR Mode High-Speed I/O Specifications

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions (201)	Maximum
Parallel Rapid I/O	00001111	2	128	640 data transitions
r araner Rapid 1/0	10010000	4	64	640 data transitions
Miscellaneous	10101010	8	32	640 data transitions
	01010101	8	32	640 data transitions

Soft CDR Mode High-Speed I/O Specifications

Table 2-44: High-Speed I/O Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.

Symbol	Conditions		C3, I3L		C4, I4		Unit	
	Conditions	Min	Тур	Мах	Min	Тур	Мах	Onic
Soft-CDR ppm tolerance	—		_	300		—	300	± ppm





⁽²⁰¹⁾ This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

DLL Range Specifications

Table 2-47: DLL Range Specifications for Arria V GZ Devices

Arria V GZ devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

Parameter	C3, I3L	C4, I4	Unit
DLL operating frequency range	300 - 890	300 - 890	MHz

DQS Logic Block Specifications

Table 2-48: DQS Phase Offset Delay Per Setting for Arria V GZ Devices

The typical value equals the average of the minimum and maximum values.

The delay settings are linear with a cumulative delay variation of 40 ps for all speed grades. For example, when using a -3 speed grade and applying a 10-phase offset setting to a 90° phase shift at 400 MHz, the expected average cumulative delay is $[625 \text{ ps} + (10 \times 11 \text{ ps}) \pm 20 \text{ ps}] = 735 \text{ ps} \pm 20 \text{ ps}$.

Speed Grade	Min	Мах	Unit	
C3, I3L	8	15	ps	
C4, I4	8	16	ps	

Table 2-49: DQS Phase Shift Error Specification for DLL-Delayed Clock (t_{DQS_PSERR}) for Arria V GZ Devices

This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a -3 speed grade is ± 84 ps or ± 42 ps.

Number of DQS Delay Buffers	C3, I3L	C4, I4	Unit
1	30	32	ps
2	60	64	ps
3	90	96	ps

Related Information

- Configuration, Design Security, and Remote System Upgrades in Arria V Devices For more information about the reconfiguration input for the ALTREMOTE_UPDATE IP core, refer to the "User Watchdog Timer" section.
- Configuration, Design Security, and Remote System Upgrades in Arria V Devices For more information about the reset_timer input for the ALTREMOTE_UPDATE IP core, refer to the "Remote System Upgrade State Machine" section.

User Watchdog Internal Oscillator Frequency Specification

Table 2-65: User Watchdog Internal Oscillator Frequency Specifications

Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz

I/O Timing

Altera offers two ways to determine I/O timing—the Excel-based I/O Timing and the Quartus II Timing Analyzer.

Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis.

The Quartus II Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete placeand-route.

Related Information

Arria V Devices Documentation page

For the Excel-based I/O Timing spreadsheet

Arria V GZ Device Datasheet

Altera Corporation



⁽²²⁶⁾ This is equivalent to strobing the reconfiguration input of the ALTREMOTE_UPDATE IP core high for the minimum timing specification. For more information, refer to the "Remote System Upgrade State Machine" section in the Configuration, Design Security, and Remote System Upgrades in Arria V Devices chapter.

⁽²²⁷⁾ This is equivalent to strobing the reset_timer input of the ALTREMOTE_UPDATE IP core high for the minimum timing specification. For more information, refer to the "User Watchdog Timer" section in the Configuration, Design Security, and Remote System Upgrades in Arria V Devices chapter.

Date	Version	Changes
June 2016	2016.06.20	 Changed column heading from "Value" to "Maximum" in the "Pin Capacitance for Arria V GZ Devices" table. Changed the minimum supported data rate range values from "1000" to "2000" in the "ATX PLL Specifications for Arria V GZ Devices" table. Added the supported data rates for the following output standards using true LVDS output buffer types in the "High-Speed Clock Specifications for Arria V GZ Devices" table: True RSDS output standard: data rates of up to 230 Mbps True mini-LVDS output standard: data rates of up to 340 Mbps
December 2015	2015.12.16	 Removed the CDR ppm tolerance specification from the "Receiver Specifications for Arria V GZ Devices" table. Removed transmitter rise and fall time specifications from the "Transmitter Specifications for Arria V GZ Devices" table. Changed the .rbf sizes in the "Uncompressed .rbf Sizes for Arria V GZ Devices" table. Added a footnote to the "Transmitter High-Speed I/O Specifications for Arria V GZ Devices" table.
June 2015	2015.06.16	 Changed the conditions for the reference clock rise and fall time and added a note to the condition in the "Reference Clock Specifications for Arria V GZ Devices" table. Added a note to the "Minimum differential eye opening at receiver serial input pins" specification in the "Receiver Specifications for Arria V GZ Devices" table.
January 2015	2015.01.30	 Added 240-Ω to the "OCT Calibration Accuracy Specifications for Arria V GZ Devices" table. Changed the CDR PPM tolerance spec in the "Receiver Specifications for Arria V GZ Devices" table. Added additional max data rate for fPLL in the "Fractional PLL Specifications for Arria V GZ Devices" table.

